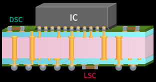
FCBGA (EPS)

개요 OVERVIEW

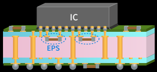
Capacitor 내장하여 고성능 반도체 Package의 PI 특성 개선

- 응용분야 : HPC, AI 가속기, 전장용 등

DSC : Die Side Capacitor
LSC : Land Side Capacitor
EPS : Embedded Passive Substrate



[일반 FCBGA]

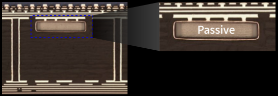


[FCBGA (EPS)]

차별화 DIFFERENTIATION

Thick Core 내 Passive 내장 기술 확보

- Passive보다 두꺼운 Core에 내장 가능
  · IC와 Capacitor간 거리 감소 (DSC (~10㎜) >> LSC (~2㎜) > EPS (~0.2㎜))
- 내부 신뢰성 Pass 완료



주요 사양 KEY SPECIFICATIONS

기판 층수	10층
Core 두께	400~1200㎛
회로 (Line/Space)	9/12㎛
Embedding Cap. Size	1005/0610

※ DSC : Die Side Capacitor, LSC : Land Side Capacitor, EPS : Embedded Passive Substrate